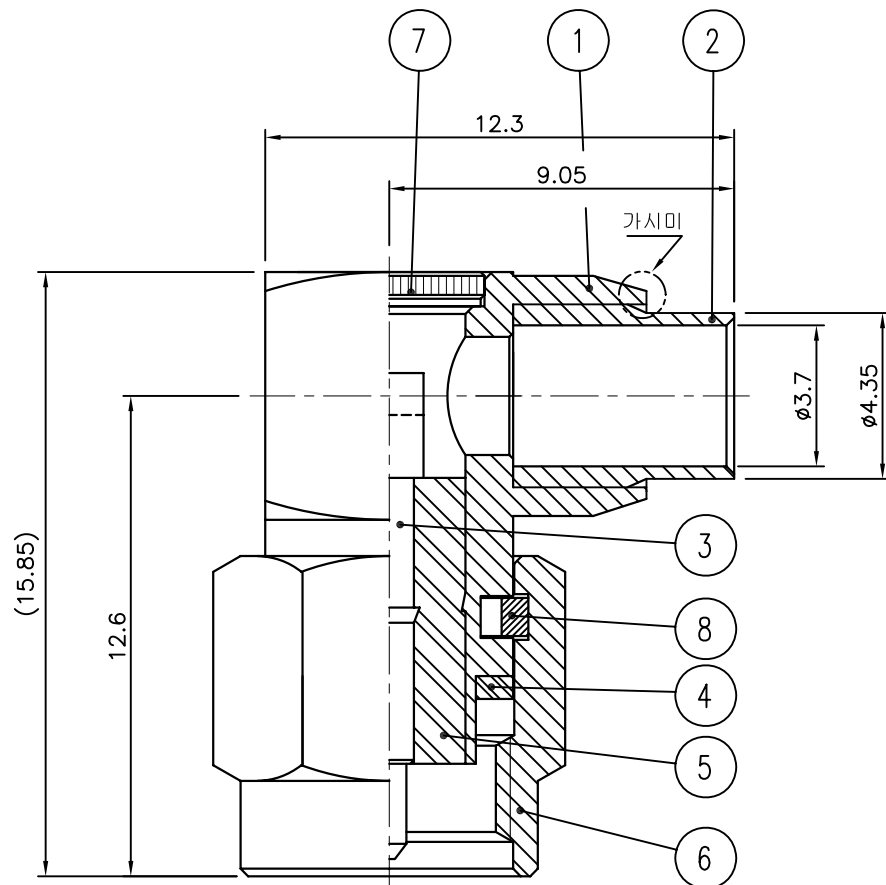
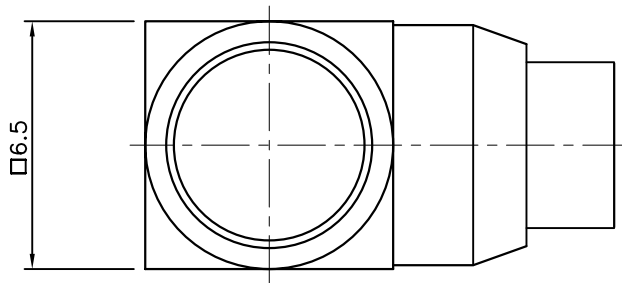
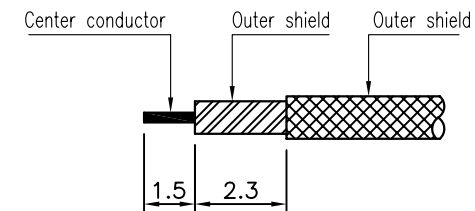
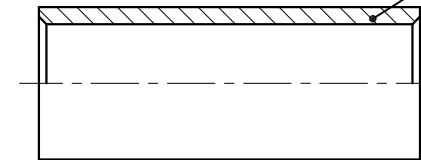




REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	I.C.KIM	I.C.KIM	2013.02.22.
1	[설번No.201608-0002] BODY 치수에 맞춰 COVER 변경	H.J.LEE	I.C.KIM	2016.08.10.



Trim cable to dimension

9	FERRULE	1	MBsBD	Nickel Plate	DFE00034-5/1
8	RING	1	SUS	부동태 처리	DSR00002-5/1
7	COVER	1	MBsBD	Nickel Plate	DCO00114-5/1 DCO00031-5/3
6	CAP	1	MBsBD	Nickel Plate	DCU00005-5/2
5	INSULATOR	1	TEFLON		DIN01015-N/1
4	GASKET	1	SILICONE RUB		DGK00004-N/1
3	CONTACT	1	MBsBD	Gold Plate	DCT00299-5/1
2	BODY (B)	1	MBsBD	Gold Plate	DBD03251-5/1
1	BODY (A)	1	ZnDC	Nickel Plate (3~4μm)	DBD02994-5/3
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2016. 08. 10.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	I.C.KIM	
MATERIAL		CHECKED BY		KJ COMTECH CO.,LTD. TITLE SMA50 CABLE PL 141
		DRAWN BY	H.J.LEE	
FINISH		SCALE	UNIT	A4 DWG NO. CN02749-7/3 REVISION 1 SHEET 1 of 1
		3/1	mm	